

Type number	Package	Package description	Total product weight
74HC30PW	SOT402-1	TSSOP14	52.22900 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935189030118	12	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Nijmegen, Netherlands; Suzhou, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.03114	77.86000	0.05963
		Polymer	Acrylic resin	Proprietary	0.00607	15.18000
		Resin system	Proprietary	0.00278	6.96000	0.00533
		subTotal		0.04000	100.00000	0.07659
Die	Doped silicon	Silicon (Si)	7440-21-3	0.61937	100.00000	1.18588
		subTotal		0.61937	100.00000	1.18588
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	19.04564	97.47000	36.46564
		Iron (Fe)	7439-89-6	0.46896	2.40000	0.89789
		Phosphorous (P)	7723-14-0	0.00586	0.03000	0.01122
		Zinc (Zn)	7440-66-6	0.01954	0.10000	0.03741
		subTotal		19.54000	100.00000	37.41216
Mould Compound	Additive	Non hazardous	Proprietary	1.48896	4.70000	2.85083
	Filler	Silica fused	60676-86-0	25.02720	79.00000	47.91821
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	1.90080	6.00000	3.63936
	Pigment	Carbon black	1333-86-4	0.06336	0.20000	0.12131
	Polymer	1.4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	1.26720	4.00000	2.42624
		Non hazardous	Proprietary	1.29888	4.10000	2.48689
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.63360	2.00000	1.21312
	subTotal		31.68000	100.00000	60.65596	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00290	1.00000	0.00555
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.28130	97.00000	0.53859
		Palladium (Pd)	7440-05-3	0.00580	2.00000	0.01110
		subTotal		0.29000	100.00000	0.55524
Wire	Pure metal	Copper (Cu)	7440-50-8	0.05963	100.00000	0.11417
		subTotal		0.05963	100.00000	0.11417

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